



1.5-Gbps LVDS/LVPECL/CML-TO-CML TRANSLATOR/REPEATER

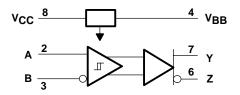
FEATURES

- Provides Level Translation From LVDS or LVPECL to CML, Repeating From CML to CML
- Signaling Rates¹ up to 1.5 Gbps
- CML Compatible Output Directly Drives Devices With 3.3-V, 2.5-V, or 1.8-V Supplies
- Total Jitter < 70 ps
- Low 100 ps (Max) Part-To-Part Skew
- Wide Common-Mode Receiver Capability Allows Direct Coupling of Input Signals
- 25 mV of Receiver Input Threshold Hysteresis Over 0-V to 4-V Common-Mode Range
- Propagation Delay Times, 800 ps Maximum
- 3.3-V Supply Operation
- Available in SOIC and MSOP Packages

APPLICATIONS

- Level Translation
- 622-MHz Central Office Clock Distribution
- High-Speed Network Routing
- Wireless Basestations
- Low Jitter Clock Repeater

FUNCTIONAL DIAGRAM



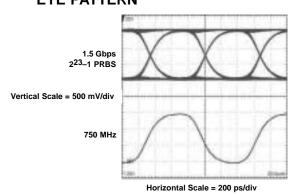
DESCRIPTION

This high-speed translator/repeater is designed for signaling rates up to 1.5 Gbps to support various high-speed network routing applications. The driver output is compatible with current-mode logic (CML) levels, and directly drives 50- Ω or 25- Ω loads connected to 1.8-V, 2.5-V, or 3.3-V nominal supplies. The capability for direct connection to the loads may eliminate the need for coupling capacitors. The receiver input is compatible with LVDS (TIA/EIA–644), LVPECL, and CML signaling levels. The receiver tolerates a wide common-mode voltage range, and may also be directly coupled to the signal source. The internal data path from input to output is fully differential for low noise generation and low pulse-width distortion.

The V_{BB} pin is an internally generated voltage supply to allow operation with a single-ended LVPECL input. For single-ended LVPECL input operation, the unused differential input is connected to V_{BB} as a switching reference voltage. When used, decouple V_{BB} with a 0.01- μ F capacitor and limit the current sourcing or sinking to 400 μ A. When not used, V_{BB} should be left open.

This device is characterized for operation from -40° C to 85° C.

EYE PATTERN



V_{CC} = 3.3 V, T_A = 25°C, $|V_{ID}|$ = 200 mV, V_{IC} = 1.2 V, V_{TT} = 3.3 V, R_T = 50 Ω

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

¹The signaling rate of a line is the number of voltage transitions that are made per second expressed in the units bps (bits per second).





These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ORDERING INFORMATION

PART NUMBER	PART MARKING	PACKAGE	STATUS
SN65CML100D	CML100	SOIC	Production
SN65CML100DGK	NWB	MSOP	Production

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range unless otherwise noted $\!\!\! (1) \!\!\!\!$

			UNIT		
Supply voltage range,(2)	Vcc	-0.5 V to 4 V			
Sink/source, I _{BB}		±0.5 mA			
Voltage range, (A, B, Y, Z)		0 V to 4.3 V		
	Human Body Model(3)	A, B, Y, Z, and GND	±5 kV		
Electrostatic discharge		All pins	±2 kV		
	Charged-DeviceModel ⁽⁴⁾ All pins		±1500 V		
Continuous power dissipa	ation	•	See Dissipation Rating Table		
Storage temperature range, T _{Stg}		−65°C to 150°C			
Lead temperature 1,6 mn	n (1/16 inch) from case for 10 s	econds	260°C		

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

		MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}		3	3.3	3.6	V
	3.3-V nominal supply at terminator	3	3.3	3.6	.,
Terminator supply voltage, VTT	2.5-V nominal supply at terminator	2.375	2.5	2.625	V
	1.8-V nominal supply at terminator	1.7		1.9	V
Magnitude of differential input voltage V	Magnitude of differential input voltage V _{ID}			1	V
Input voltage (any combination of commo	n-mode or input signals)	0		4	V
Output current, V _{BB}				400	μΑ
Operating free-air temperature, T _A		-40		85	°C

⁽²⁾ All voltage values, except differential I/O bus voltages, are with respect to network ground terminal.

⁽³⁾ Tested in accordance with JEDEC Standard 22, Test Method A114-A.7.

⁽⁴⁾ Tested in accordance with JEDEC Standard 22, Test Method C101.



PACKAGE DISSIPATION RATINGS

PACKAGE	$T_A \le 25^{\circ}C$ POWER RATING	DERATING FACTOR ⁽¹⁾ ABOVE T _A = 25°C	T _A = 85°C POWER RATING
DGK	425 mW	3.4 mW/°C	221 mW
D	725 mW	5.8 mW/°C	377 mW

⁽¹⁾ This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.

DEVICE CHARACTERISTICS

	PARAMETER	MIN	NOM	MAX	UNIT
ICC	Supply current, device only		9	12	mA
V_{BB}	Switching reference voltage(1)	1890	1950	2010	mV

⁽¹⁾ VBB parameter varies 1:1 with VCC

INPUT ELECTRICAL CHARACTERISTICS

over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP(1)	MAX	UNIT	
V _{IT+}	Positive-going differential input voltage threshold	Our Firms 4 and Table 4			100) (
V _{IT} –	Negative-going differential input voltage threshold	See Figure 1 and Table 1	-100			mV	
VID(HYS)	Differential input voltage hysteresis, V _{IT+} - V _{IT-}			25		mV	
	Lamest assessed (A. a. B. innesta)	V _I = 0 V or 2.4 V, Second input at 1.2 V	-20		20	•	
Ц	Input current (A or B inputs)	V _I = 4 V, Second input at 1.2 V			33	μΑ	
l _l (OFF)	Power off input current (A or B inputs)	V _{CC} = 1.5 V, V _I = 0 V or 2.4 V, Second input at 1.2 V	-20		20	μА	
.(0)		$V_{CC} = 1.5 \text{ V}, V_I = 4 \text{ V}, \text{ Second input at } 1.2 \text{ V}$			33	·	
IIO	Input offset current (I _{IA} - I _{IB})	$V_{IA} = V_{IB}$, $0 \le V_{IA} \le 4 \text{ V}$	-6		6	μΑ	
_		V _I = 0.4 sin (4E6πt) + 0.5 V	3				
Ci	Differential input capacitance	VCC = 0 V		3		pF	

⁽¹⁾ All typical values are at 25°C and with a 3.3-V supply.

OUTPUT ELECTRICAL CHARACTERISTICS

over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP(1)	MAX	UNIT
Vон	Output high voltage(2)	$R_T = 50 \Omega$, $V_{TT} = 3 V$ to 3.6 V or	V _{TT} -60	V _{TT} –10	VTT	mV
VOL	Output low voltage(2)	$V_{TT} = 2.5 V \pm 5\%$,	V _{TT} -1100	V _{TT} -800	V _{TT} -640	mV
IVODI	Differential output voltage magnitude	See Figure 2	640	780	1000	mV
Vон	Output high voltage ⁽³⁾	$R_T = 25 \Omega$, $V_{TT} = 3 V$ to 3.6 V or	VTT-60	V _{TT} -10	VTT	mV
VOL	Output low voltage(3)	$V_{TT} = 2.5 V \pm 5\%$	V _{TT} -550	VTT-400	VTT-320	mV
IVODI	Differential output voltage magnitude	See Figure 2	320	390	500	mV
VOH	Output high voltage ⁽²⁾		V _{TT} -170	V _{TT} –10	VTT	mV
VOL	Output low voltage ⁽²⁾	$R_T = 50 \Omega$, $V_{TT} = 1.8 V \pm 5\%$, See Figure 2	VTT-1100	VTT-800	VTT-640	mV
IVODI	Differential output voltage magnitude		570	780	1000	mV
VOH	Output high voltage ⁽³⁾		VTT-85	V _{TT} -10	VTT	mV
VOL	Output low voltage(3)	$R_T = 25 \Omega$, $V_{TT} = 1.8 V \pm 5\%$, See Figure 2	VTT-500	VTT-400	V _{TT} -320	mV
IVODI	Differential output voltage magnitude		285	390	500	mV
	Difference of a location of the second	V _I = 0.4 sin (4E6πt) + 0.5 V		3		
Co	Differential output capacitance	VCC = 0 V		3		pF

⁽¹⁾ All typical values are at 25°C and with a 3.3-V supply.

 ⁽²⁾ Outputs are terminated through 50-Ω resistors to V_{TT}, CML level specifications are referenced to V_{TT} and tracks 1:1 with variation of V_{TT}.
 (3) Outputs are terminated through 25-Ω resistors to V_{TT}, CML level specifications are referenced to V_{TT} and tracks 1:1 with variation of V_{TT}.



SWITCHING CHARACTERISTICS

over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	NOM ⁽¹⁾	MAX	UNIT
tPLH	Propagation delay time, low-to-high-level output		250		800	ps
tPHL	Propagation delay time, high-to-low-level output	$R_T = 50 \Omega \text{ or } R_T = 25 \Omega,$	250		800	ps
t _r	Differential output signal rise time (20% – 80%)	See Figure 4			300	ps
tf	Differential output signal fall time (20% – 80%)				300	ps
tsk(p)	Pulse skew (tpHL - tpLH)(2)			0	50	ps
tsk(pp)	Part-to-part skew(3)	V _{ID} = 0.2 V			100	ps
tjit(per)	Period jitter, rms (1 standard deviation) ⁽⁴⁾	750 MHz clock input ⁽⁵⁾		1	5	ps
tjit(cc)	Cycle-to-cycle jitter (peak) ⁽⁴⁾	750 MHz clock input ⁽⁶⁾		8	27	ps
tjit(pp)	Peak-to-peakjitter ⁽⁴⁾	1.5 Gbps 2 ²³ –1 PRBS input ⁽⁷⁾		30	70	ps
tjit(det)	Deterministic jitter, peak-to-peak ⁽⁴⁾	1.5 Gbps 2 ⁷ –1 PRBS input(8)		25	65	ps

⁽¹⁾ All typical values are at 25°C and with a 3.3-V supply.

⁽²⁾ $t_{Sk(p)}$ is the magnitude of the time difference between the t_{PLH} and t_{PHL} .

⁽³⁾ t_{sk(pp)} is the magnitude of the difference in propagation delay times between any specified terminals of two devices when both devices operate with the same supply voltages, at the same temperature, and have identical packages and test circuits.

⁽⁴⁾ Jitter parameters are ensured by design and characterization. Measurements are made with a Tektronix TDS6604 oscilloscope running Tektronix TDSJIT3 software. Agilent E4862B stimulus system jitter 2 ps t_{jit(per)}, 16 ps t_{jit(cc)}, 25 ps t_{jit(pp)}, and 10 ps t_{jit(det)} has been subtracted from the values.

⁽⁵⁾ V_{ID} = 200 mV, 50% duty cycle, V_{IC} = 1.2 V, t_{Γ} = t_{f} ≤ 25 ns (20% to 80%), measured over 1000 samples.

⁽⁶⁾ $V_{ID} = 200 \text{ mV}$, 50% duty cycle, $V_{IC} = 1.2 \text{ V}$, $t_f = t_f \le 25 \text{ ns}$ (20% to 80%). (7) $V_{ID} = 200 \text{ mV}$, $V_{IC} = 1.2 \text{ V}$, $t_f = t_f \le 0.25 \text{ ns}$ (20% to 80%), measured over 100k samples. (8) $V_{ID} = 200 \text{ mV}$, $V_{IC} = 1.2 \text{ V}$, $t_f = t_f \le 0.25 \text{ ns}$ (20% to 80%). Deterministic jitter is sum of pattern dependent jitter and pulse width distortion.



PARAMETER MEASUREMENT INFORMATION

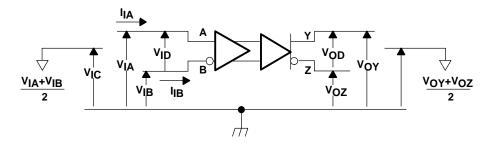


Figure 1. Voltage and Current Definitions

Table 1. Maximum Receiver Input Voltage Threshold

APPLIED VOLTAGES		RESULTING DIFFERENTIAL INPUT VOLTAGE	RESULTING COMMON- MODE INPUT VOLTAGE	OUTPUT
VIA	V _{IB}	V _{ID}	V _{IC}	
1.25 V	1.15 V	100 mV	1.2 V	Н
1.15 V	1.25 V	-100 mV	1.2 V	L
4.0 V	3.9 V	100 mV	3.95 V	Н
3.9 V	4. 0 V	-100 mV	3.95 V	L
0.1 V	0.0 V	100 mV	0.5 V	Н
0.0 V	0.1 V	–100 mV	0.5 V	L
1.7 V	0.7 V	1000 mV	1.2 V	Н
0.7 V	1.7 V	-1000 mV	1.2 V	L
4.0 V	3.0 V	1000 mV	3.5 V	Н
3.0 V	4.0 V	-1000 mV	3.5 V	L
1.0 V	0.0 V	1000 mV	0.5 V	Н
0.0 V	1.0 V	-1000 mV	0.5 V	L

H = high level, L = low level

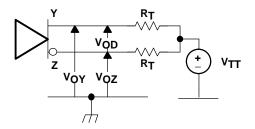


Figure 2. Output Voltage Test Circuit

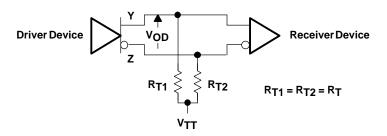
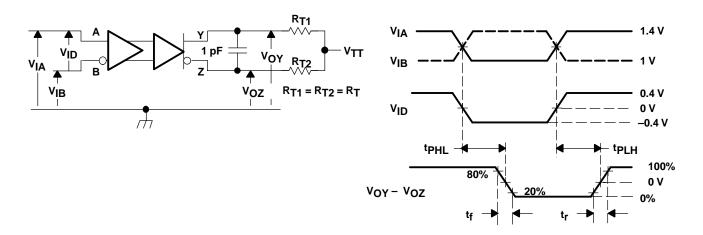


Figure 3. Typical Termination for Output Driver



PARAMETER MEASUREMENT INFORMATION



NOTE: All input pulses are supplied by a generator having the following characteristics: t_Γ or $t_\Gamma \le 0.25$ ns, pulse repetition rate (PRR) = 50 Mpps, pulse width = 10 \pm 0.2 ns. C_L includes instrumentation and fixture capacitance within 0,06 mm of the D.U.T. Measurement equipment provides a bandwidth of 5 GHz minimum.

Figure 4. Timing Test Circuit and Waveforms

PIN ASSIGNMENTS

D AND DGK PACKAGE (TOP VIEW)



PIN DESCRIPTIONS

PIN	FUNCTION	
A, B	Differential inputs	
Y, Z	Differentialoutputs	
V _{BB}	Reference voltage output	
Vcc	Power supply	
GND	Ground	
NC	No connect	

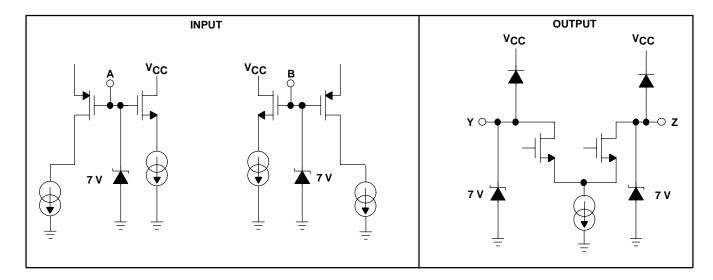
FUNCTION TABLE

DIFFERENTIAL INPUT	OUTP	UTS
$V_{ID} = V_A - V_B$	Υ	Z
$V_{ID} \ge 100 \text{ mV}$	Н	L
$-100 \text{ mV} < \text{V}_{\text{ID}} < 100 \text{ mV}$?	?
$V_{ID} \le -100 \text{ mV}$	L	Н
Open	?	?

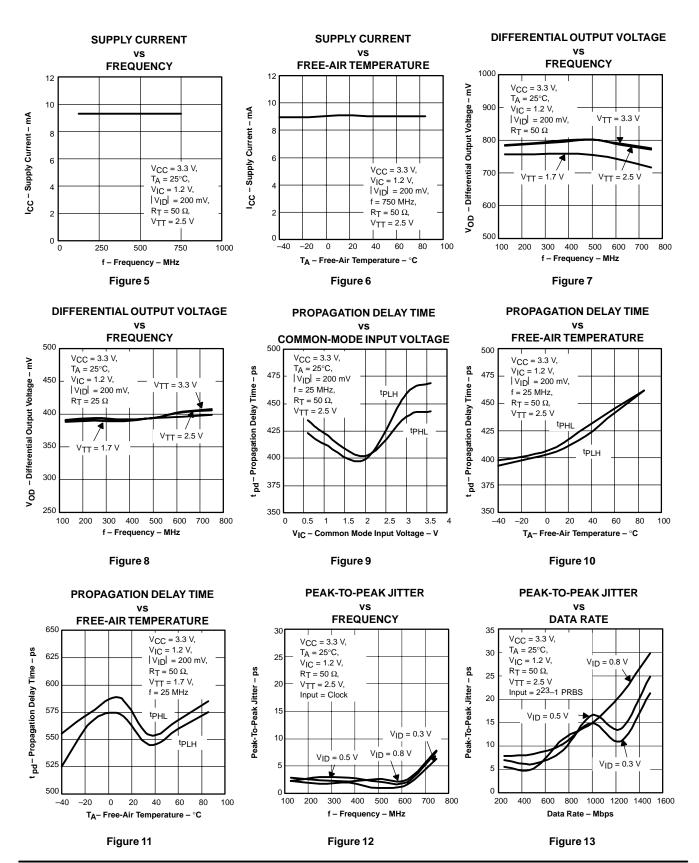
H = high level, L = low level, ? = intermediate



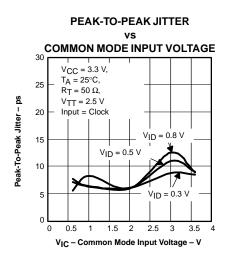
EQUIVALENT INPUT AND OUTPUT SCHEMATIC DIAGRAMS

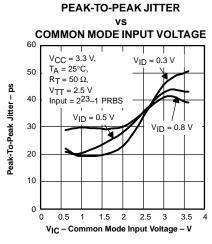












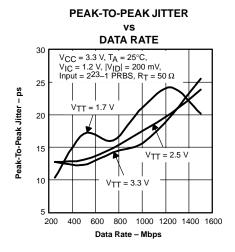
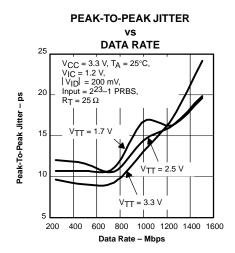
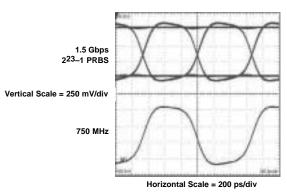


Figure 14 Figure 15 Figure 16

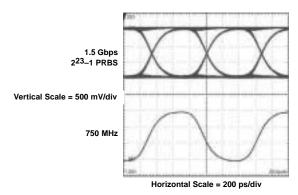




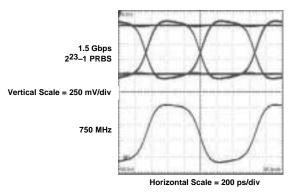


 $\rm V_{CC}$ = 3.3 V, T_A = 25 °C, $|\rm \,V_{ID}|$ = 200 mV, $\rm V_{IC}$ = 1.2 V, V_{TT} = 3.3 V, R_T = 25 Ω

Figure 18



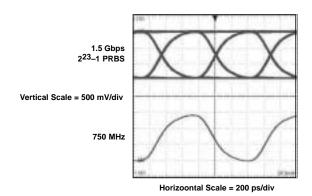
 $\rm V_{CC}$ = 3.3 V, T_{A} = 25 ^{\circ}C, \, |V_{ID}| \, = 200 mV, V $_{IC}$ = 1.2 V, V $_{TT}$ = 2.5 V, $\,$ R $_{T}$ = 50 $\,$ $\!\Omega$



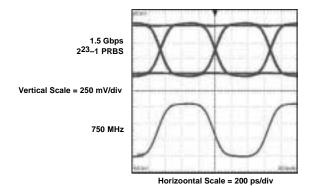
 $\rm V_{CC}$ = 3.3 V, T_A = 25 °C, $\rm |V_{ID}|$ = 200 mV, V $_{IC}$ = 1.2 V, V $_{TT}$ = 2.5 V, R $_{T}$ = 25 Ω

Figure 19 Figure 20





 $\rm V_{CC}$ = 3.3 V, T_A = 25°C, V $_{IC}$ = 1.2 V, $\rm |V_{ID}|$ = 200 mV, V $_{TT}$ = 1.7 V, R $_{T}$ = 50 Ω



 $\rm V_{CC}$ = 3.3 V, T_A = 25 $^{\circ}$ C, V $_{IC}$ = 1.2 V, $|\rm \,V_{ID}|\,$ = 200 mV, V $_{TT}$ = 1.7 V, R $_{T}$ = 25 Ω

Figure 21 Figure 22



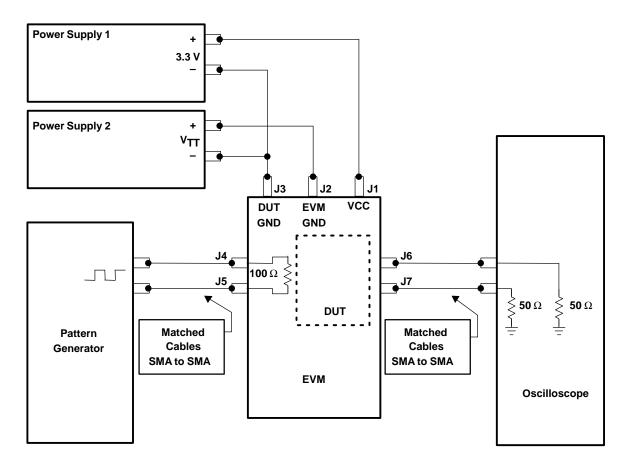


Figure 23. Jitter Setup Connections for SN65CML100



APPLICATION INFORMATION

For single-ended input conditions, the unused differential input is connected to V_{BB} as a switching reference voltage. When V_{BB} is used, decouple V_{BB} via a 0.01- μ F capacitor and limit the current sourcing or sinking to 0.4 mA. When not used, V_{BB} should be left open.

TYPICAL APPLICATION CIRCUITS (ECL, PECL, LVDS, ETC.)

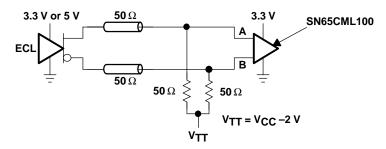


Figure 24. Low-Voltage Positive Emitter-Coupled Logic (LVPECL)

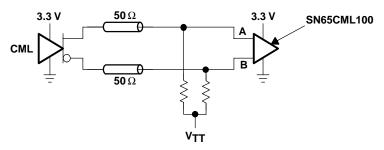


Figure 25. Current-Mode Logic (CML)

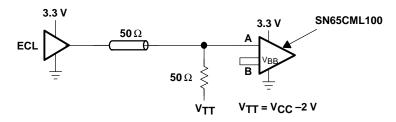


Figure 26. Single-Ended (LVPECL)

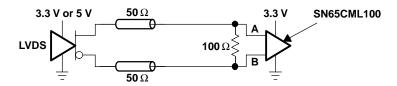


Figure 27. Low-Voltage Differential Signaling (LVDS)

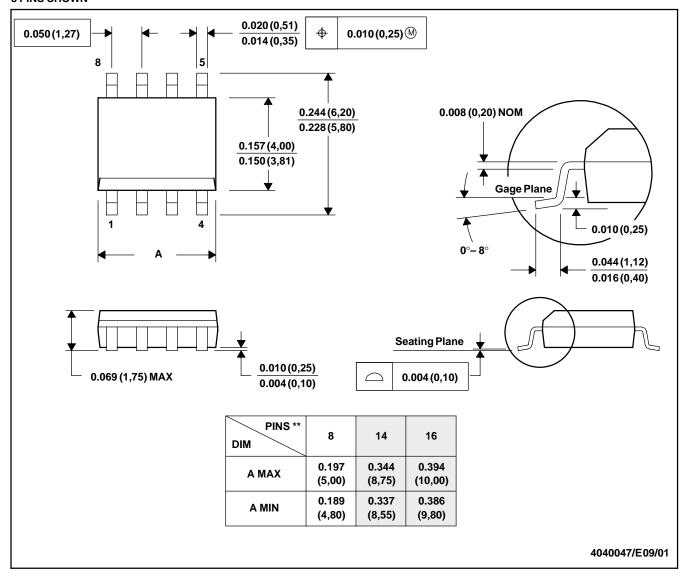


MECHANICAL DATA

D (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

8 PINS SHOWN



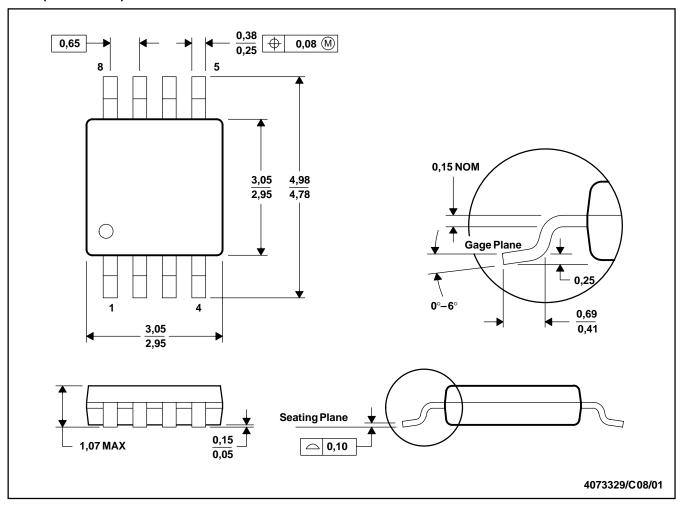
- NOTES:A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-012



MECHANICAL DATA

DGK (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.C. Body dimensions do not include mold flash or protrusion.
- D. Falls within JEDEC MO-187

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